



US 20230230947A1

(19) **United States**

(12) **Patent Application Publication**  
**Sakuma**

(10) **Pub. No.: US 2023/0230947 A1**

(43) **Pub. Date: Jul. 20, 2023**

(54) **SOLDER TRANSFER INTEGRATED  
CIRCUIT PACKAGING**

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(21) Appl. No.: **18/179,431**

(22) Filed: **Mar. 7, 2023**

**Related U.S. Application Data**

(62) Division of application No. 17/348,162, filed on Jun. 15, 2021, now Pat. No. 11,631,650.

**Publication Classification**

(51) **Int. Cl.**  
**H01L 23/00** (2006.01)  
**B23K 1/005** (2006.01)

**H01L 21/50** (2006.01)

**H01L 21/60** (2006.01)

(52) **U.S. Cl.**

CPC ..... **H01L 24/14** (2013.01); **B23K 1/0056**  
(2013.01); **H01L 21/50** (2013.01); **H01L 24/75**  
(2013.01); **H01L 2021/60112** (2013.01)

(57)

**ABSTRACT**

An approach for transferring solder to a laminate structure in IC (integrated circuit) packaging is disclosed. The approach comprises of a device and method of applying the device. The device comprises of a substrate, a laser ablation layer and solder layer. The device is made by depositing a laser ablation layer onto a glass/silicon substrate and plenty of solder powder/solder pillar is further deposited onto the laser ablation layer. The laminate packaging substrate includes pads with a pad surface finishing layer made from gold. The solder layer of the device is bonded to the laminate packaging substrate. Once bonded, using laser to irradiate the laser ablation layer, the substrate is removed from the laminate.

